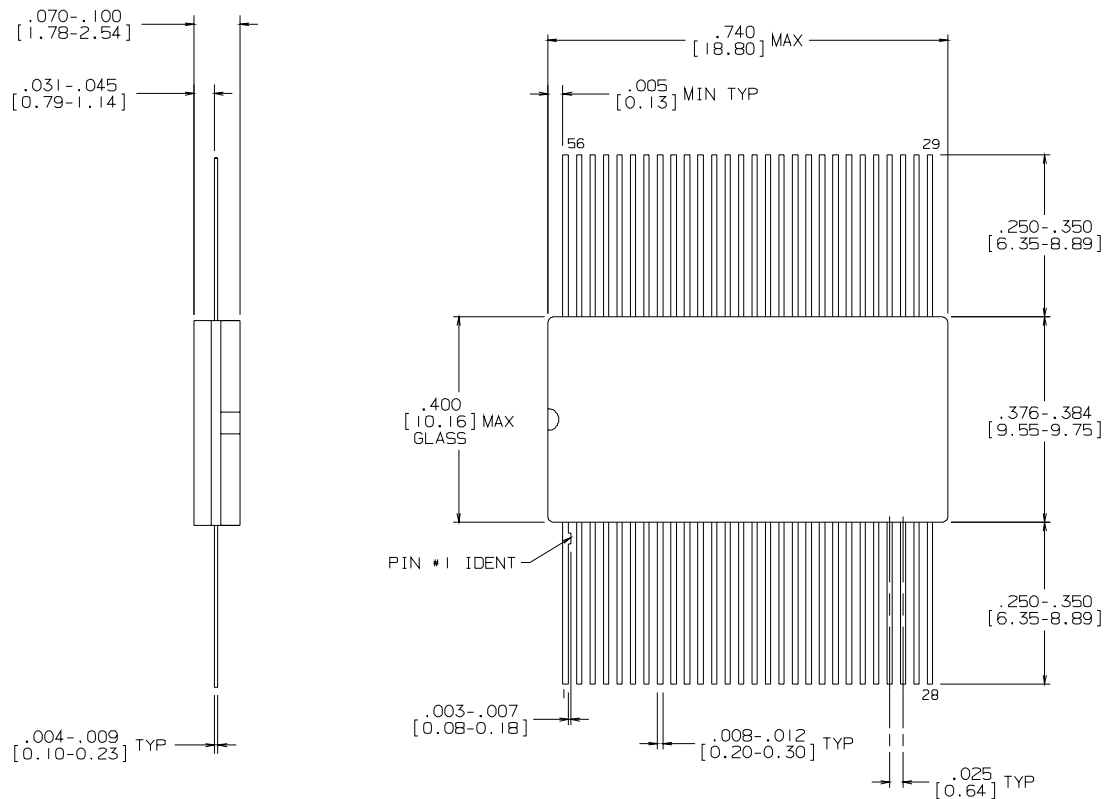


R E V I S I O N S				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	09282	08/17/92	TL/SC
B	DIM .003-.007[0.08-0.18] WAS .006-.010[0.15-0.25]; DIM .031-.045[0.79-1.14] WAS .040-.054[1.02-1.37]	09486	01/25/93	MS/



NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH:
200 MICROINCHES/ 5.08 MICROMETERS MINIMUM SOLDER
MEASURED AT THE CREST OF THE MAJOR FLATS.
2. THE LEAD FINISH, NICKEL UNDERPLATE, AND BASIS METAL
SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
3. REFERENCE JEDEC METRIC BALLOT JC-11.10-92-75, ITEM 10-320,
VARIATION AB, DATED JULY 9, 1992.

MIL-M-38510
CONFIGURATION CONTROL

CONTROLLING DIMENSION: INCH					
APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION			
DRAWN T. LEQUANG	08/17/92	2900 Semiconductor Drive, Santa Clara, CA 95052-8090			
DFTG. CHK.		CERPAC, 56 LEAD, .025 LEAD PITCH			
ENGR. CHK.					
APPROVAL					
PROJECTION 		SCALE N/A	SIZE C	DRAWING NUMBER MKT-WA56A	REV B
		DO NOT SCALE DRAWING		SHEET	OF